Renesas Electronics America Inc - M306N4MGT-165FPUFQ Datasheet

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	M16C/60
Core Size	16-Bit
Speed	20MHz
Connectivity	CANbus, I²C, IEBus, SIO, UART/USART
Peripherals	DMA, WDT
Number of I/O	87
Program Memory Size	256KB (256K x 8)
Program Memory Type	Mask ROM
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-QFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m306n4mgt-165fpufq

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M16C/6N Group (M16C/6N4)

Renesas MCU

REJ03B0003-0240
Rev.2.40
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1. Overview

The M16C/6N Group (M16C/6N4) of MCUs are built using the high-performance silicon gate CMOS process using the M16C/60 Series CPU core and are packaged in 100-pin plastic molded QFP and LQFP. These MCUs operate using sophisticated instructions featuring a high level of instruction efficiency. With 1 Mbyte of address space, they are capable of executing instructions at high speed. Being equipped with two CAN (Controller Area Network) modules in the M16C/6N Group (M16C/6N4), the MCU is suited to drive automotive and industrial control systems. The CAN modules comply with the 2.0B specification. In addition, this MCU contains a multiplier and DMAC which combined with fast instruction processing capability, makes it suitable for control of various OA, communication, and industrial equipment which requires high-speed arithmetic/logic operations.

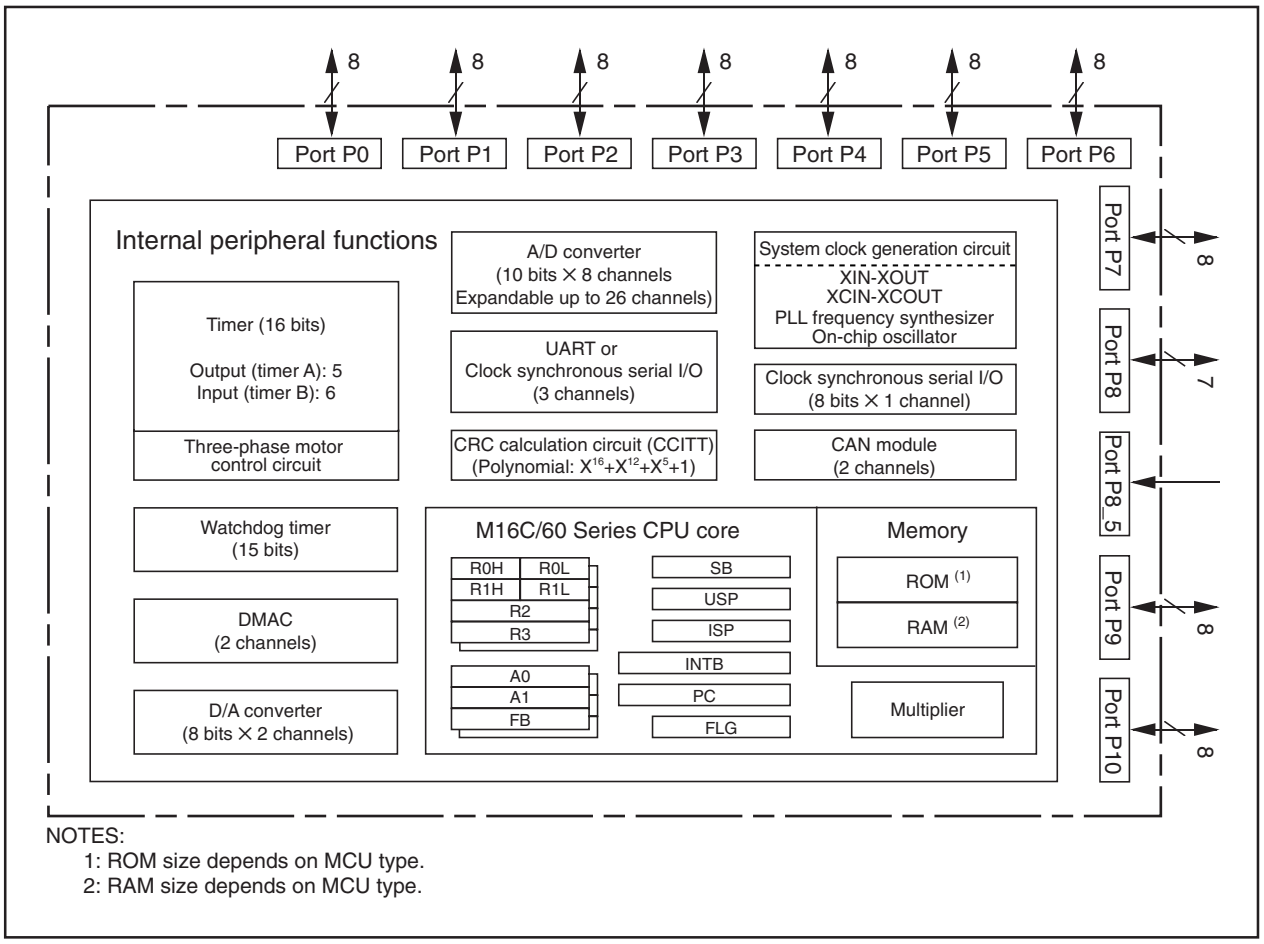
1.1 Applications

- Automotive, industrial control systems and other automobile, other (T/V-ver. product)
- Car audio and industrial control systems, other (Normal-ver. product)

Specifications written in this manual are believed to be accurate, but are not guaranteed to be entirely free of error. Specifications in this manual may be changed for functional or performance improvements. Please make sure your manual is the latest edition.

1.3 Block Diagram

Figure 1.1 shows a Block Diagram.

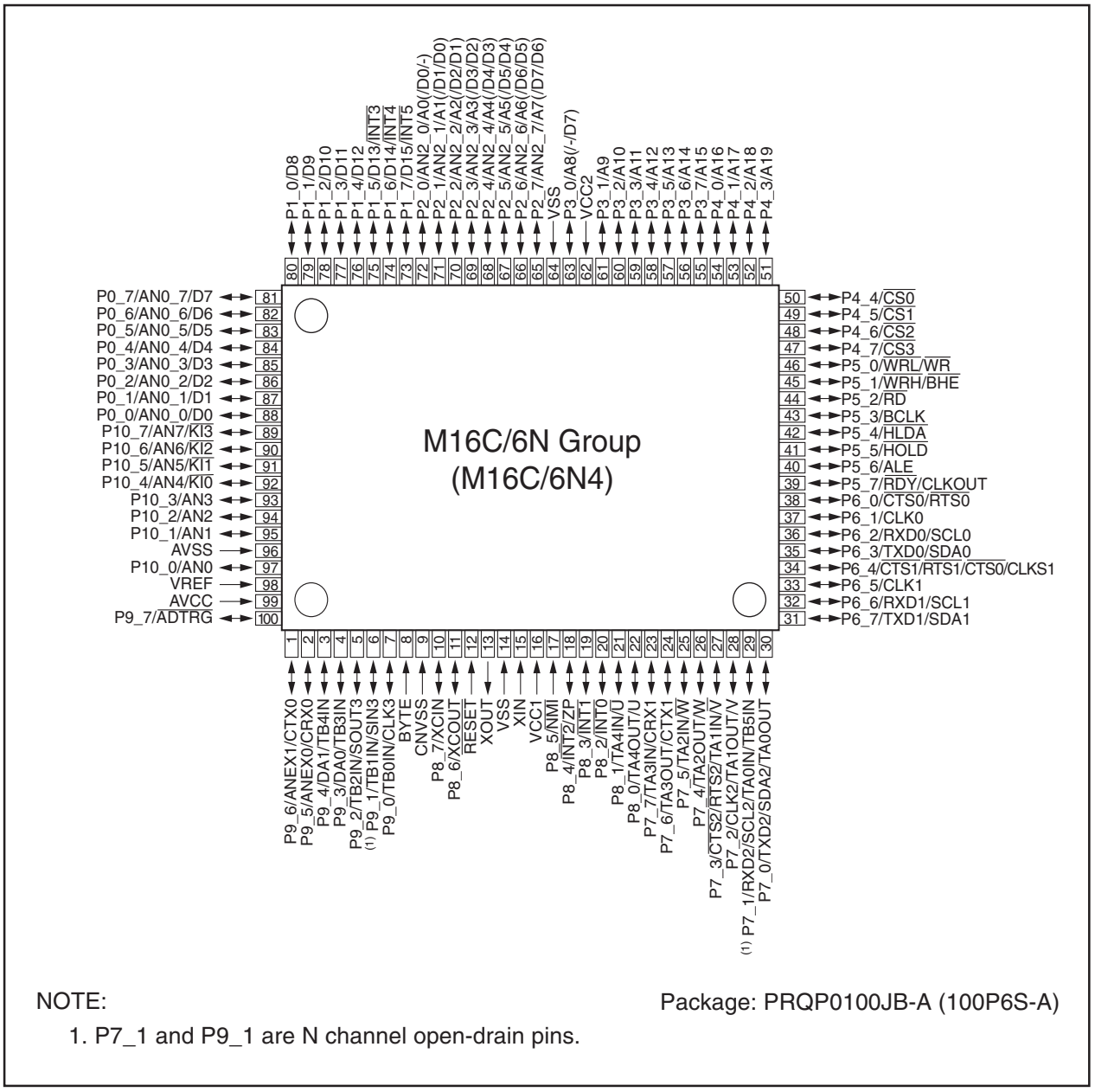


NOTES:
1: ROM size depends on MCU type.
2: RAM size depends on MCU type.

Figure 1.1 Block Diagram

1.5 Pin Assignments

Figures 1.3 and 1.4 show the Pin Assignment (Top View). Tables 1.3 and 1.4 list the List of Pin Names.



NOTE:
1. P7_1 and P9_1 are N channel open-drain pins.

Package: PRQP0100JB-A (100P6S-A)

Figure 1.3 Pin Assignments (Top View) (1)

Table 1.6 Pin Functions (2)

Signal Name	Pin Name	I/O Type	Description
Main clock input	XIN	I	I/O pins for the main clock oscillation circuit. Connect a ceramic resonator or crystal oscillator between XIN and XOUT (1).
Main clock output	XOUT	O	To use the external clock, input the clock from XIN and leave XOUT open.
Sub clock input	XCIN	I	I/O pins for a sub clock oscillation circuit. Connect a crystal oscillator between XCIN and XCOUT (1).
Sub clock output	XCOUT	O	To use the external clock, input the clock from XCIN and leave XCOUT open.
BCLK output	BCLK	O	Outputs the BCLK signal.
Clock output	CLKOUT	O	The clock of the same cycle as fC, f8, or f32 is output.
INT interrupt input	INT0 to INT5	I	Input pins for the INT interrupt.
NMI interrupt input	NMI	I	Input pin for the NMI interrupt.
Key input interrupt input	KI0 to KI3	I	Input pins for the key input interrupt.
Timer A	TA0OUT to TA4OUT	I/O	These are timer A0 to timer A4 I/O pins.
	TA0IN to TA4IN	I	These are timer A0 to timer A4 input pins.
	ZP	I	Input pin for the Z-phase.
Timer B	TB0IN to TB5IN	I	These are timer B0 to timer B5 input pins.
Three-phase motor control output	U, U, V, V, W, W	O	These are Three-phase motor control output pins.
Serial interface	CTS0 to CTS2	I	These are transmit control input pins.
	RTS0 to RTS2	O	These are receive control output pins.
	CLK0 to CLK3	I/O	These are transfer clock I/O pins.
	RXD0 to RXD2	I	These are serial data input pins.
	SIN3	I	These are serial data input pins.
	TXD0 to TXD2	O	These are serial data output pins.
	SOUT3	O	These are serial data output pins.
	CLKS1	O	This is output pin for transfer clock output from multiple pins function.
I^2C mode	SDA0 to SDA2	I/O	These are serial data I/O pins.
	SCL0 to SCL2	I/O	These are transfer clock I/O pins. (however, SCL2 for the N-channel open drain output.)
Reference voltage input	VREF	I	Applies the reference voltage for the A/D converter and D/A converter.
A/D converter	AN0 to AN7 AN0_0 to AN0_7 AN2_0 to AN2_7	I	Analog input pins for the A/D converter.
	ADTRG	I	This is an A/D trigger input pin.
	ANEX0	I/O	This is the extended analog input pin for the A/D converter, and is the output in external op-amp connection mode.
	ANEX1	I	This is the extended analog input pin for the A/D converter.
D/A converter	DA0, DA1	O	These are the output pins for the D/A converter.
CAN module	CRX0, CRX1	I	These are the input pins for the CAN module.
	CTX0, CTX1	O	These are the output pins for the CAN module.

I: Input O: Output I/O: Input/Output

NOTE:
1. Ask the oscillator maker the oscillation characteristic.

Table 4.3 SFR Information (3)

Address	Register	Symbol	After Reset
0080h	CAN0 Message Box 2: Identifier / DLC		XXh
0081h			XXh
0082h			XXh
0083h			XXh
0084h			XXh
0085h			XXh
0086h	CAN0 Message Box 2: Data Field		XXh
0087h			XXh
0088h			XXh
0089h			XXh
008Ah			XXh
008Bh			XXh
008Ch			XXh
008Dh			XXh
008Eh	CAN0 Message Box 2: Time Stamp		XXh
008Fh			XXh
0090h	CAN0 Message Box 3: Identifier / DLC		XXh
0091h			XXh
0092h			XXh
0093h			XXh
0094h			XXh
0095h			XXh
0096h	CAN0 Message Box 3: Data Field		XXh
0097h			XXh
0098h			XXh
0099h			XXh
009Ah			XXh
009Bh			XXh
009Ch			XXh
009Dh			XXh
009Eh	CAN0 Message Box 3: Time Stamp		XXh
009Fh			XXh
00A0h	CAN0 Message Box 4: Identifier / DLC		XXh
00A1h			XXh
00A2h			XXh
00A3h			XXh
00A4h			XXh
00A5h			XXh
00A6h	CAN0 Message Box 4: Data Field		XXh
00A7h			XXh
00A8h			XXh
00A9h			XXh
00AAh			XXh
00ABh			XXh
00ACh			XXh
00ADh			XXh
00AEh	CAN0 Message Box 4: Time Stamp		XXh
00AFh			XXh
00B0h	CAN0 Message Box 5: Identifier / DLC		XXh
00B1h			XXh
00B2h			XXh
00B3h			XXh
00B4h			XXh
00B5h			XXh
00B6h	CAN0 Message Box 5: Data Field		XXh
00B7h			XXh
00B8h			XXh
00B9h			XXh
00BAh			XXh
00BBh			XXh
00BCh			XXh
00BDh			XXh
00BEh	CAN0 Message Box 5: Time Stamp		XXh
00BFh			XXh

X: Undefined

Table 4.4 SFR Information (4)

Address	Register	Symbol	After Reset
00C0h	CAN0 Message Box 6: Identifier / DLC		XXh
00C1h			XXh
00C2h			XXh
00C3h			XXh
00C4h			XXh
00C5h			XXh
00C6h	CAN0 Message Box 6: Data Field		XXh
00C7h			XXh
00C8h			XXh
00C9h			XXh
00CAh			XXh
00CBh			XXh
00CCh			XXh
00CDh			XXh
00CEh	CAN0 Message Box 6: Time Stamp		XXh
00CFh			XXh
00D0h	CAN0 Message Box 7: Identifier / DLC		XXh
00D1h			XXh
00D2h			XXh
00D3h			XXh
00D4h			XXh
00D5h			XXh
00D6h	CAN0 Message Box 7: Data Field		XXh
00D7h			XXh
00D8h			XXh
00D9h			XXh
00DAh			XXh
00DBh			XXh
00DCh			XXh
00DDh			XXh
00DEh	CAN0 Message Box 7: Time Stamp		XXh
00DFh			XXh
00E0h	CAN0 Message Box 8: Identifier / DLC		XXh
00E1h			XXh
00E2h			XXh
00E3h			XXh
00E4h			XXh
00E5h			XXh
00E6h	CAN0 Message Box 8: Data Field		XXh
00E7h			XXh
00E8h			XXh
00E9h			XXh
00EAh			XXh
00EBh			XXh
00ECh			XXh
00EDh			XXh
00EEh	CAN0 Message Box 8: Time Stamp		XXh
00EFh			XXh
00F0h	CAN0 Message Box 9: Identifier / DLC		XXh
00F1h			XXh
00F2h			XXh
00F3h			XXh
00F4h			XXh
00F5h			XXh
00F6h	CAN0 Message Box 9: Data Field		XXh
00F7h			XXh
00F8h			XXh
00F9h			XXh
00FAh			XXh
00FBh			XXh
00FCh			XXh
00FDh			XXh
00FEh	CAN0 Message Box 9: Time Stamp		XXh
00FFh			XXh

X: Undefined

Table 4.12 SFR Information (12)

Address	Register	Symbol	After Reset
02C0h	CAN1 Message Box 6: Identifier / DLC		XXh
02C1h			XXh
02C2h			XXh
02C3h			XXh
02C4h			XXh
02C5h			XXh
02C6h	CAN1 Message Box 6: Data Field		XXh
02C7h			XXh
02C8h			XXh
02C9h			XXh
02CAh			XXh
02CBh			XXh
02CCh			XXh
02CDh			XXh
02CEh	CAN1 Message Box 6: Time Stamp		XXh
02CFh			XXh
02D0h	CAN1 Message Box 7: Identifier / DLC		XXh
02D1h			XXh
02D2h			XXh
02D3h			XXh
02D4h			XXh
02D5h			XXh
02D6h	CAN1 Message Box 7: Data Field		XXh
02D7h			XXh
02D8h			XXh
02D9h			XXh
02DAh			XXh
02DBh			XXh
02DCh			XXh
02DDh			XXh
02DEh	CAN1 Message Box 7: Time Stamp		XXh
02DFh			XXh
02E0h	CAN1 Message Box 8: Identifier / DLC		XXh
02E1h			XXh
02E2h			XXh
02E3h			XXh
02E4h			XXh
02E5h			XXh
02E6h	CAN1 Message Box 8: Data Field		XXh
02E7h			XXh
02E8h			XXh
02E9h			XXh
02EAh			XXh
02EBh			XXh
02ECh			XXh
02EDh			XXh
02EEh	CAN1 Message Box 8: Time Stamp		XXh
02EFh			XXh
02F0h	CAN1 Message Box 9: Identifier / DLC		XXh
02F1h			XXh
02F2h			XXh
02F3h			XXh
02F4h			XXh
02F5h			XXh
02F6h	CAN1 Message Box 9: Data Field		XXh
02F7h			XXh
02F8h			XXh
02F9h			XXh
02FAh			XXh
02FBh			XXh
02FCh			XXh
02FDh			XXh
02FEh	CAN1 Message Box 9: Time Stamp		XXh
02FFh			XXh

X: Undefined

5. Electrical Characteristics

5.1 Electrical Characteristics (T/V-ver.)

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter		Condition	Rated Value	Unit
V_{CC}	Supply voltage (VCC1 = VCC2)		VCC = AVCC	–0.3 to 6.5	V
AV_{CC}	Analog supply voltage		VCC = AVCC	–0.3 to 6.5	V
V_I	Input voltage	$\overline{RESET}$, CNVSS, BYTE, P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0, P7_2 to P7_7, P8_0 to P8_7, P9_0, P9_2 to P9_7, P10_0 to P10_7, VREF, XIN		–0.3 to VCC+0.3	V
		P7_1, P9_1		–0.3 to 6.5	V
V_O	Output voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0, P9_2 to P9_7, P10_0 to P10_7, XOUT		–0.3 to VCC+0.3	V
		P7_1, P9_1		–0.3 to 6.5	V
P_d	Power dissipation		Topr = 25°C	700	mW
T_{opr}	Operating ambient temperature	During MCU operation		T version: –40 to 85 V version: –40 to 125 (option)	°C
		During flash memory program and erase operation		0 to 60	
T_{stg}	Storage temperature			–65 to 150	°C

option: All options are on request basis.

Table 5.6 A/D Conversion Characteristics (1)

Symbol	Parameter		Measuring Condition		Standard			Unit
					Min.	Typ.	Max.	
–	Resolution		VREF = VCC				10	Bit
INL	Integral nonlinearity error	10 bits	VREF = VCC = 5 V	ANEX0, ANEX1 input, AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input			±3	LSB
				External operation amp connection mode			±7	LSB
		8 bits	VREF = AVCC = VCC = 5 V				±2	LSB
–	Absolute accuracy	10 bits	VREF = VCC = 5 V	ANEX0, ANEX1 input, AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input			±3	LSB
				External operation amp connection mode			±7	LSB
		8 bits	VREF = AVCC = VCC = 5 V				±2	LSB
DNL	Differential nonlinearity error						±1	LSB
–	Offset error						±3	LSB
–	Gain error						±3	LSB
R_{LADDER}	Resistor ladder		VREF = VCC		10		40	kΩ
t_{CONV}	10-bit conversion time, sample & hold available		VREF = VCC = 5 V, ϕAD = 10 MHz		3.3			µs
	8-bit conversion time, sample & hold available		VREF = VCC = 5 V, ϕAD = 10 MHz		2.8			µs
t_{SAMP}	Sampling time				0.3			µs
V_{REF}	Reference voltage				2.0		V_{CC}	V
V_{IA}	Analog input voltage				0		V_{REF}	V

NOTES:
1. Referenced to VCC = AVCC = VREF = 4.2 to 5.5 V, VSS = AVSS = 0 V, –40 to 85°C unless otherwise specified.
2. ϕAD frequency must be 10 MHz or less.
3. When sample & hold is disabled, ϕAD frequency must be 250kHz or more in addition to a limit of NOTE 2.
   When sample & hold is enabled, ϕAD frequency must be 1MHz or more in addition to a limit of NOTE 2.

Table 5.7 D/A conversion Characteristics (1)

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
–	Resolution				8	Bits
–	Absolute accuracy				1.0	%
t_{su}	Setup time				3	µs
R_O	Output resistance		4	10	20	kΩ
I_{VREF}	Reference power supply input current	(NOTE 2)			1.5	mA

NOTES:
1. Referenced to VCC = AVCC = VREF = 4.2 to 5.5 V, VSS = AVSS = 0 V, –40 to 85°C unless otherwise specified.
2. This applies when using one D/A converter, with the DAi register (i = 0, 1) for the unused D/A converter set to 00h. The resistor ladder of the A/D converter is not included. Also, the I_{VREF} will flow even if VREF is disconnected by the ADCON1 register.

Timing Requirements

VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.11 Timer A Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	100		ns
$t_{w(TAH)}$	TAiIN input HIGH pulse width	40		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	40		ns

Table 5.12 Timer A Input (Gating Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	400		ns
$t_{w(TAH)}$	TAiIN input HIGH pulse width	200		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	200		ns

Table 5.13 Timer A Input (External Trigger Input in One-shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	200		ns
$t_{w(TAH)}$	TAiIN input HIGH pulse width	100		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	100		ns

Table 5.14 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(TAH)}$	TAiIN input HIGH pulse width	100		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	100		ns

Table 5.15 Timer A Input (Counter Increment/decrement Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(UP)}$	TAiOUT input cycle time	2000		ns
$t_{w(UPH)}$	TAiOUT input HIGH pulse width	1000		ns
$t_{w(UPL)}$	TAiOUT input LOW pulse width	1000		ns
$t_{su(UP-TIN)}$	TAiOUT input setup time	400		ns
$t_{h(TIN-UP)}$	TAiOUT input hold time	400		ns

Table 5.16 Timer A Input (Two-phase Pulse Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	800		ns
$t_{su(TAIN-TAOUT)}$	TAiOUT input setup time	200		ns
$t_{su(TAOUT-TAIN)}$	TAiIN input setup time	200		ns

Timing Requirements

VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.17 Timer B Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time (counted on one edge)	100		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width (counted on one edge)	40		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width (counted on one edge)	40		ns
$t_{c(TB)}$	TBiIN input cycle time (counted on both edges)	200		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width (counted on both edges)	80		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width (counted on both edges)	80		ns

Table 5.18 Timer B Input (Pulse Period Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time	400		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width	200		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width	200		ns

Table 5.19 Timer B Input (Pulse Width Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time	400		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width	200		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width	200		ns

Table 5.20 A/D Trigger Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{C(AD)}$	$\overline{\text{ADTRG}}$ input cycle time (trigger able minimum)	1000		ns
$t_{w(ADL)}$	$\overline{\text{ADTRG}}$ input LOW pulse width	125		ns

Table 5.21 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200		ns
$t_{w(CKH)}$	CLKi input HIGH pulse width	100		ns
$t_{w(CKL)}$	CLKi input LOW pulse width	100		ns
$t_{d(C-Q)}$	TXDi output delay time		80	ns
$t_{h(C-Q)}$	TXDi hold time	0		ns
$t_{su(D-C)}$	RXDi input setup time	70		ns
$t_{h(C-D)}$	RXDi input hold time	90		ns

Table 5.22 External Interrupt $\overline{\text{INTi}}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{\text{INTi}}$ input HIGH pulse width	250		ns
$t_{w(INL)}$	$\overline{\text{INTi}}$ input LOW pulse width	250		ns

Switching Characteristics

VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85 °C unless otherwise specified)

Table 5.25 Memory Expansion Mode and Microprocessor Mode (for 2- to 3-wait setting, external area access and multiplexed bus selection)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	Figure 5.2		25	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		4		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		(NOTE 1)		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			25	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		4		ns
$t_{h(RD-CS)}$	Chip select output hold time (in relation to RD)		(NOTE 1)		ns
$t_{h(WR-CS)}$	Chip select output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			25	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			25	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data output hold time (in relation to BCLK)		4		ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(NOTE 2)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-HLDA)}$	$\overline{HLDA}$ output delay time			40	ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time (in relation to BCLK)			15	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time (in relation to BCLK)		–4		ns
$t_{d(AD-ALE)}$	ALE signal output delay time (in relation to Address)		(NOTE 3)		ns
$t_{h(ALE-AD)}$	ALE signal output hold time (in relation to Address)		(NOTE 4)		ns
$t_{d(AD-RD)}$	RD signal output delay from the end of Address		0		ns
$t_{d(AD-WR)}$	WR signal output delay from the end of Address		0		ns
$t_{dZ(RD-AD)}$	Address output floating start time			8	ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 10 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 40 \text{ [ns]}$$

n is “2” for 2-wait setting, “3” for 3-wait setting.

3. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 25 \text{ [ns]}$$

4. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 15 \text{ [ns]}$$

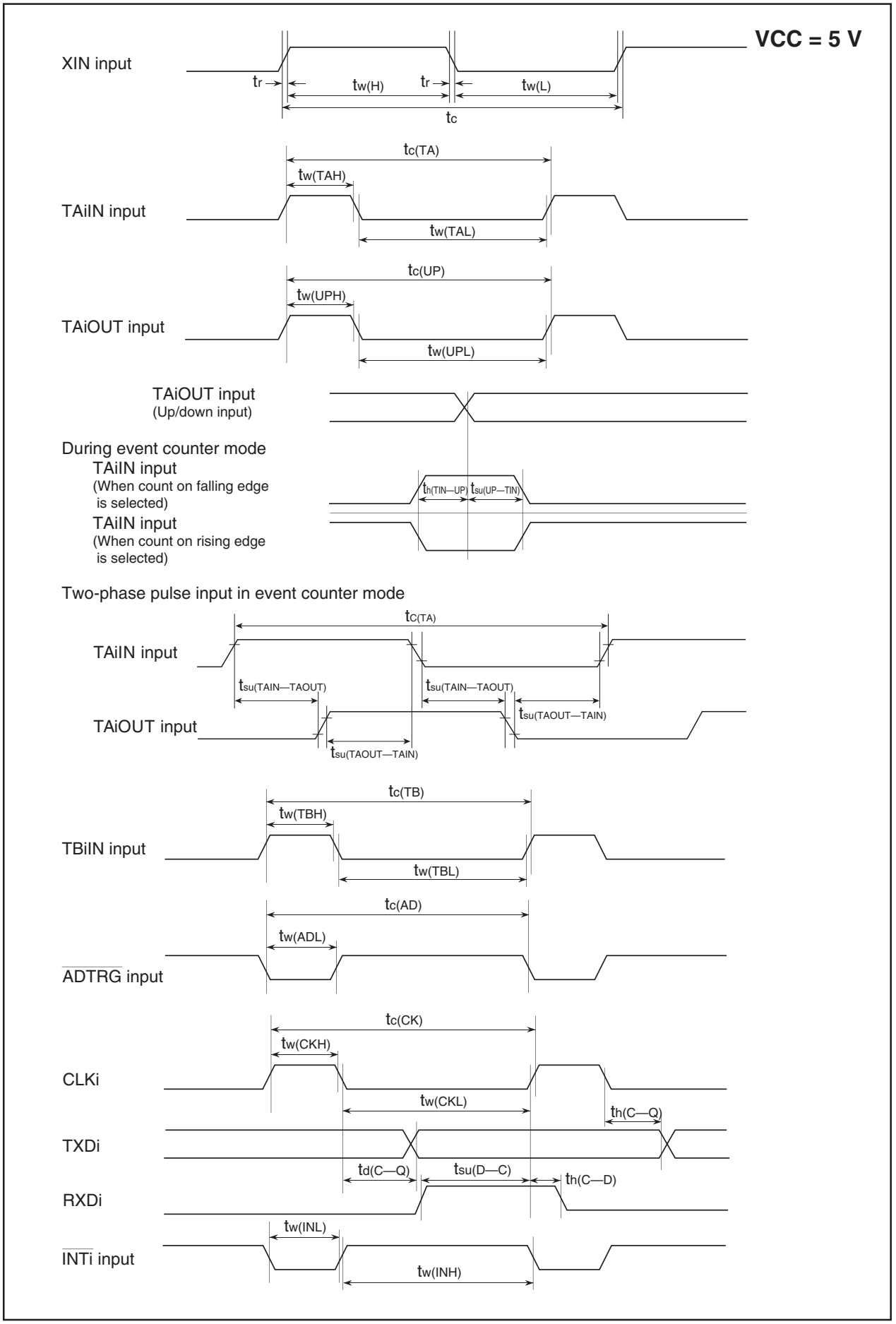


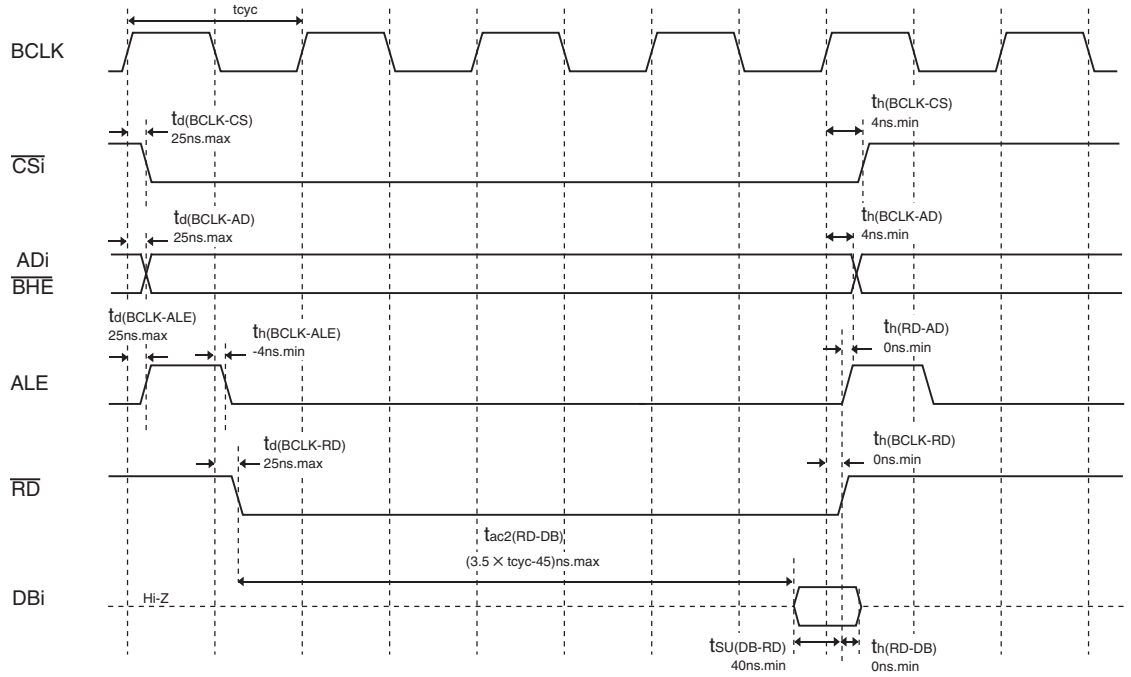
Figure 5.3 Timing Diagram (1)

Memory Expansion Mode and Microprocessor Mode

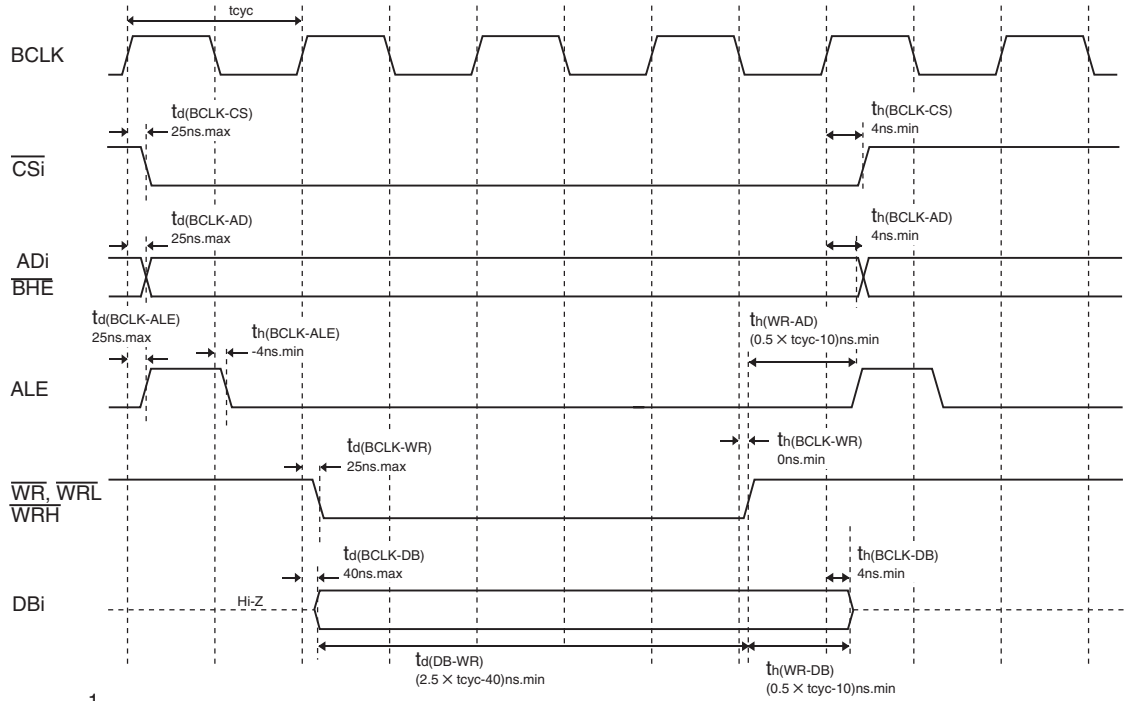
VCC = 5 V

(For 3-wait setting and external area access)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

Measuring conditions :

- VCC = 5 V
- Input timing voltage : V_{IL} = 0.8 V, V_{IH} = 2.0 V
- Output timing voltage : V_{OL} = 0.4 V, V_{OH} = 2.4 V

Figure 5.8 Timing Diagram (6)

Timing Requirements

VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.36 Timer A Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	100		ns
$t_{w(TAH)}$	TAiIN input HIGH pulse width	40		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	40		ns

Table 5.37 Timer A Input (Gating Input in Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	400		ns
$t_{w(TAH)}$	TAiIN input HIGH pulse width	200		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	200		ns

Table 5.38 Timer A Input (External Trigger Input in One-shot Timer Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	200		ns
$t_{w(TAH)}$	TAiIN input HIGH pulse width	100		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	100		ns

Table 5.39 Timer A Input (External Trigger Input in Pulse Width Modulation Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(TAH)}$	TAiIN input HIGH pulse width	100		ns
$t_{w(TAL)}$	TAiIN input LOW pulse width	100		ns

Table 5.40 Timer A Input (Counter Increment/decrement Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(UP)}$	TAiOUT input cycle time	2000		ns
$t_{w(UPH)}$	TAiOUT input HIGH pulse width	1000		ns
$t_{w(UPL)}$	TAiOUT input LOW pulse width	1000		ns
$t_{su(UP-TIN)}$	TAiOUT input setup time	400		ns
$t_{h(TIN-UP)}$	TAiOUT input hold time	400		ns

Table 5.41 Timer A Input (Two-phase Pulse Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle rime	800		ns
$t_{su(TAIN-TAOUT)}$	TAiOUT input setup time	200		ns
$t_{su(TAOUT-TAIN)}$	TAiIN input setup time	200		ns

Timing Requirements

VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.42 Timer B Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time (counted on one edge)	100		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width (counted on one edge)	40		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width (counted on one edge)	40		ns
$t_{c(TB)}$	TBiIN input cycle time (counted on both edges)	200		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width (counted on both edges)	80		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width (counted on both edges)	80		ns

Table 5.43 Timer B Input (Pulse Period Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time	400		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width	200		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width	200		ns

Table 5.44 Timer B Input (Pulse Width Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time	400		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width	200		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width	200		ns

Table 5.45 A/D Trigger Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{C(AD)}$	$\overline{\text{ADTRG}}$ input cycle time (trigger able minimum)	1000		ns
$t_{w(ADL)}$	$\overline{\text{ADTRG}}$ input LOW pulse width	125		ns

Table 5.46 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200		ns
$t_{w(CKH)}$	CLKi input HIGH pulse width	100		ns
$t_{w(CKL)}$	CLKi input LOW pulse width	100		ns
$t_{d(C-Q)}$	TXDi output delay time		80	ns
$t_{h(C-Q)}$	TXDi hold time	0		ns
$t_{su(D-C)}$	RXDi input setup time	70		ns
$t_{h(C-D)}$	RXDi input hold time	90		ns

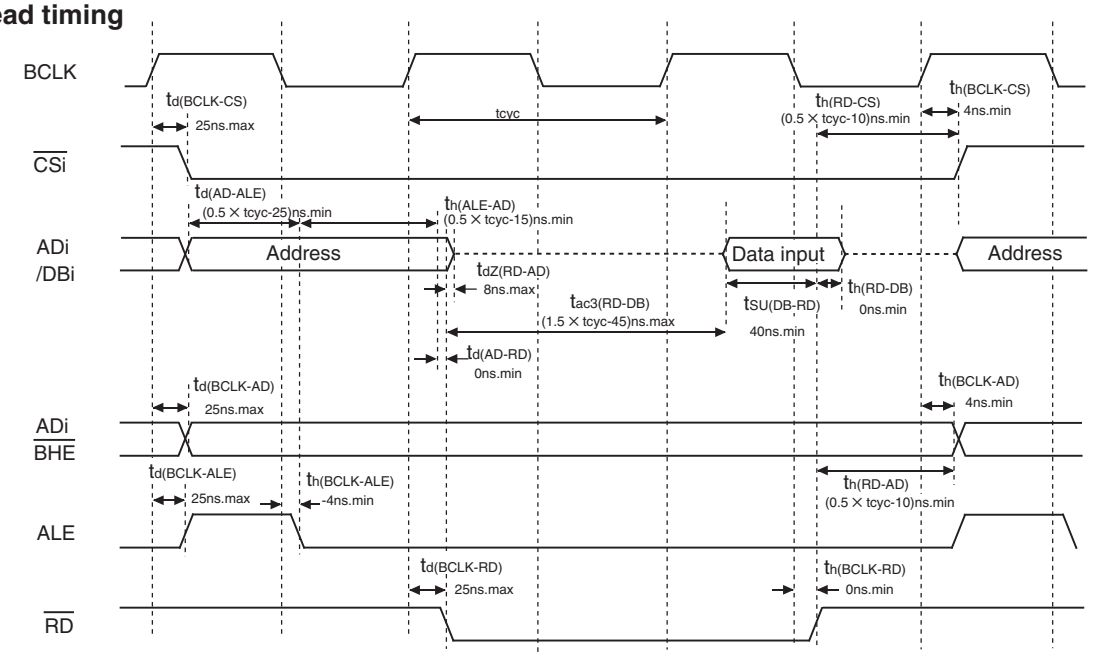
Table 5.47 External Interrupt $\overline{\text{INTi}}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{\text{INTi}}$ input HIGH pulse width	250		ns
$t_{w(INL)}$	$\overline{\text{INTi}}$ input LOW pulse width	250		ns

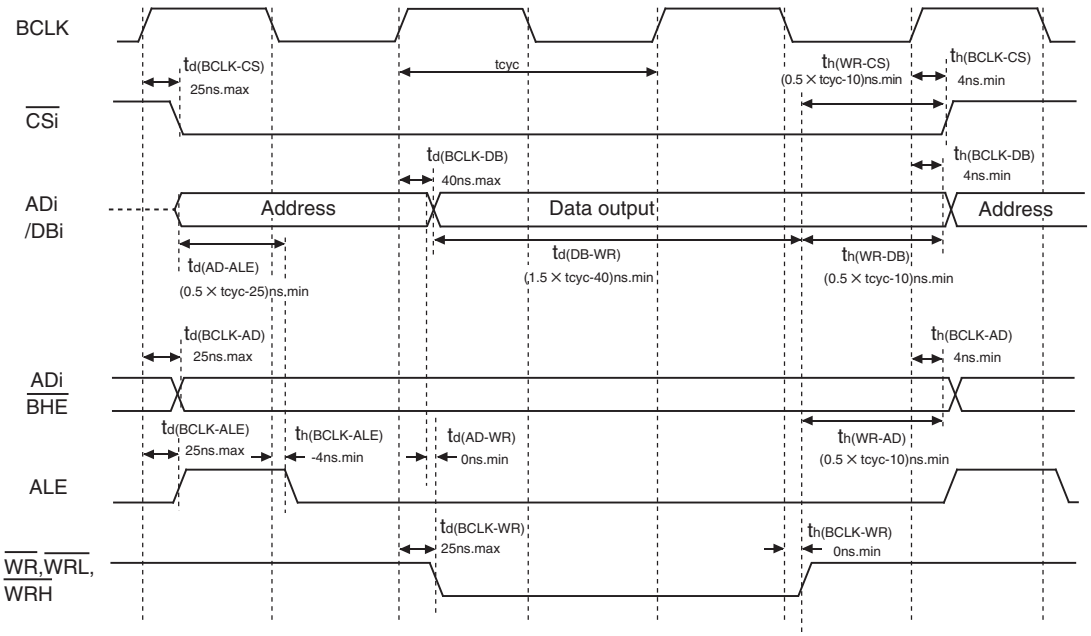
Memory Expansion Mode and Microprocessor Mode — VCC = 5 V

(For 1- or 2-wait setting, external area access and multiplexed bus selection)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

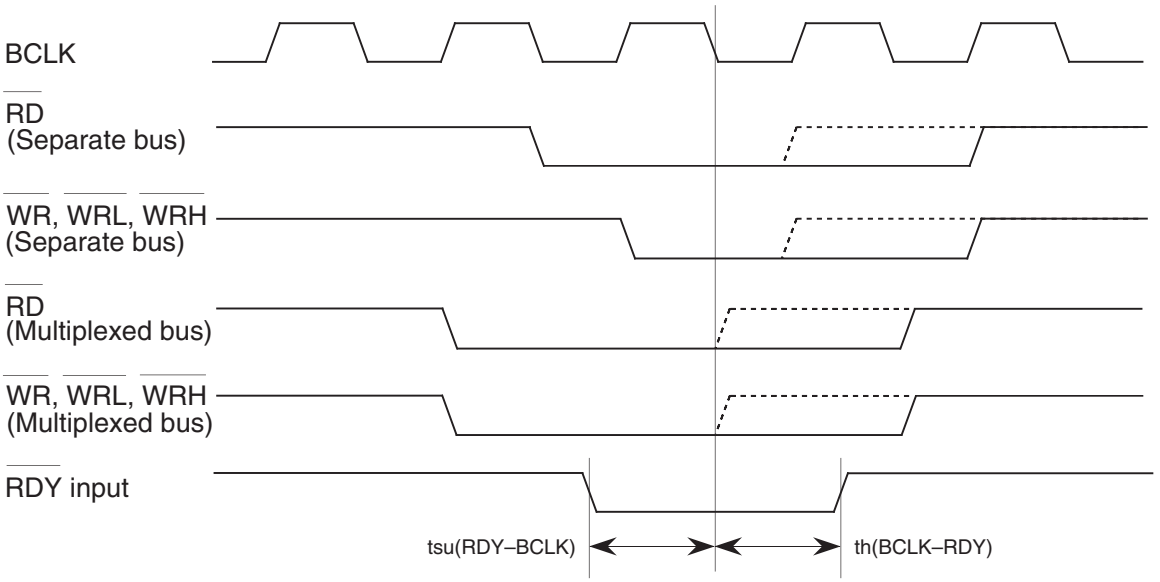
Measuring conditions :

- VCC = 5 V
- Input timing voltage : V_{IL} = 0.8 V, V_{IH} = 2.0 V
- Output timing voltage : V_{OL} = 0.4 V, V_{OH} = 2.4 V

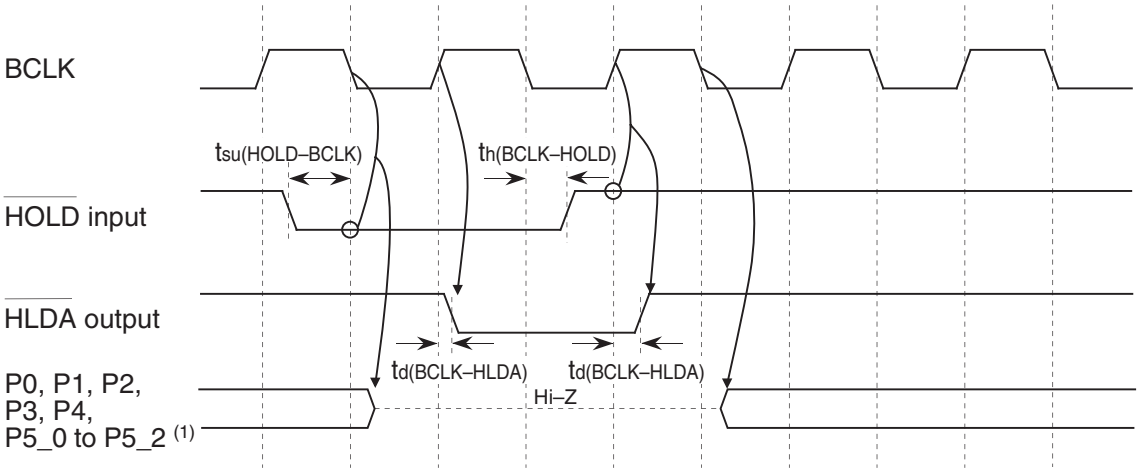
Figure 5.19 Timing Diagram (7)

Memory Expansion Mode and Microprocessor Mode **VCC = 3.3 V**

(Effective for setting with wait)



(Common to setting with wait and setting without wait)



NOTE:
1. The above pins are set to high-impedance regardless of the input level of the BYTE pin, the PM06 bit in the PM0 register, and the PM11 bit in the PM1 register.

Measuring conditions :
- VCC = 3.3 V
- Input timing voltage : Determined with V_{IL} = 0.6 V, V_{IH} = 2.7 V
- Output timing voltage: Determined with V_{OL} = 1.65 V, V_{OH} = 1.65 V

Figure 5.23 Timing Diagram (2)

REVISION HISTORY	M16C/6N Group (M16C/6N4) Data Sheet

Rev.	Date	Description	
		Page	Summary
2.00	Nov. 10, 2004	34	Table 5.6 A/D Conversion Characteristics: "Tolerance Level Impedance" is added.
		35	Table 5.8 Power Supply Circuit Timing Characteristics: "$t_{d(M-L)}$" is deleted.
			Figure 5.2 Power Supply Circuit Timing Diagram is added.
		36	Table 5.10 Memory Expansion Mode and Microprocessor Mode: "$t_{d(BCLK-HLDA)}$" is deleted.
		38	Table 5.21 Serial I/O: Min. of standard in $t_{su(D-C)}$ is revised from "30" to "70".
		39	Table 5.23 Memory Expansion Mode and Microprocessor Mode (for setting with no wait)
			• Max. of Standard in $t_{d(BCLK-ALE)}$ is revised from "25" to "15".
			• $t_{d(BCLK-HLDA)}$ is added.
		40	Table 5.24 Memory Expansion Mode and Microprocessor Mode (for 1- to 3-wait setting and external area access)
			• Max. of Standard in $t_{d(BCLK-ALE)}$ is revised from "25" to "15".
			• $t_{d(BCLK-HLDA)}$ is added.
		41	Table 5.25 Memory Expansion Mode and Microprocessor Mode (for 2- to 3-wait setting, external area access and multiplexed bus selection)
			• $t_{d(BCLK-HLDA)}$ is added.
			• Max. of Standard in $t_{d(BCLK-ALE)}$ is revised from "25" to "15".
		42	Figure 5.4 Timing Diagram (1): "XIN input" is added.
		44, 45	Figures 5.6 and 5.7 Timing Diagram (3) (4): "DB" in Read timing is revised to "DBi".
		46, 47	Figures 5.8 and 5.9 Timing Diagram (5) (6): "DB" in Write timing is revised to "DBi".
		49	Figure 5.11 Timing Diagram (8)
			• "ADi/DB" in Read/Write timing is revised to "ADi/DBi".
		50	Appendix 1. Package Dimensions: 100P6Q-A is added.
2.10	Jun. 24, 2005	–	Revised edition issued
			* The contents of product are revised. (Normal-ver. is added.)
			* Revised parts and revised contents are as follows (except for expressional change).
		2	Table 1.1 Performance outline of M16C/6N Group (M16C/6N4)
			• Performance outline of Normal-ver. is added.
		4	Table 1.2 Product List is revised. (Normal-ver. is added.)
			Figure 1.2 Type No., Memory Size, and Package:
			• "(no): Normal-ver." is added to Characteristics.
		19	Figure 4.7 SFR Information (7): NOTE 1 is revised.
		32	Table 5.4 Electrical Characteristics (1)
			• Measuring Condition of V_{OL} is revised from "I_{OL} = –200μA" to "I_{OL} = 200μA".
		33	Table 5.5 Electrical Characteristics (2): Mask ROM (5th item)
			• "f(XCIN)" is changed to "(f(BCLK)).
		34	Table 5.6 A/D Conversion Characteristics: "Tolerance Level Impedance" is deleted.
2.40	Aug. 25, 2006	–	Revised edition issued
			* Electric Characteristics of Normal-ver. is added.
			* Revised parts and revised contents are as follows (except for expressional change).
		1	1.1 Applications: Comment of Normal-ver. is added.
		4	Table 1.2 Product Information
			• Status of development is revised and NOTES 1 and 2 are added.